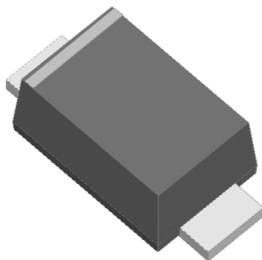


Features

Schottky chip
Ideal for surface mounted applications
Low forward voltage drop, Low power loss, high efficiency
Plastic Case Material has UL Flammability

Mechanical Data

Package: SOD123FL
Terminals: Tin Plated leads, solderable per
Mil-STD-750 Method 2026
Polarity: As marked
Molding compound meets UL 94 V-0 flammability rating,
ROHS-compliant



SOD-123FL

Maximum Ratings (Ta=25°C Unless otherwise specified)

Type Number	SYMBOL	K120	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	V
Maximum RMS Voltage	V_{RMS}	140	V
Maximum DC Blocking Voltage	V_{DC}	200	V
Maximum Average Forward Rectified Current at $T_L = 100^\circ\text{C}$	$I_{O(AV)}$	1.0	A
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load (JEDEC Method) on rated	IFSM	20.0	A
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, $T_J = 25^\circ\text{C}$		40.0	A
Current squared time @1ms ≤ t ≤ 8.3ms $T_J = 25^\circ\text{C}$, Rating of per diode	I^2t	1.7	A ² S
Maximum Forward Voltage at 1.0A DC	V_{FM}	0.92	V
Maximum Reverse Current $T_A = 25^\circ\text{C}$	IR	0.05	mA
at Rated DC Blocking Voltage $T_A = 100^\circ\text{C}$		5	mA
Typical Thermal Resistance	R_{QJA}	75.0	°C/W
Operating Junction Temperature Range	T_J	—55to+150	°C
Storage Temperature Range	T_{STG}	—55to+150	°C

FIG. 1 MAXIMUM AVERAGE FORWARD CURRENT DERATING

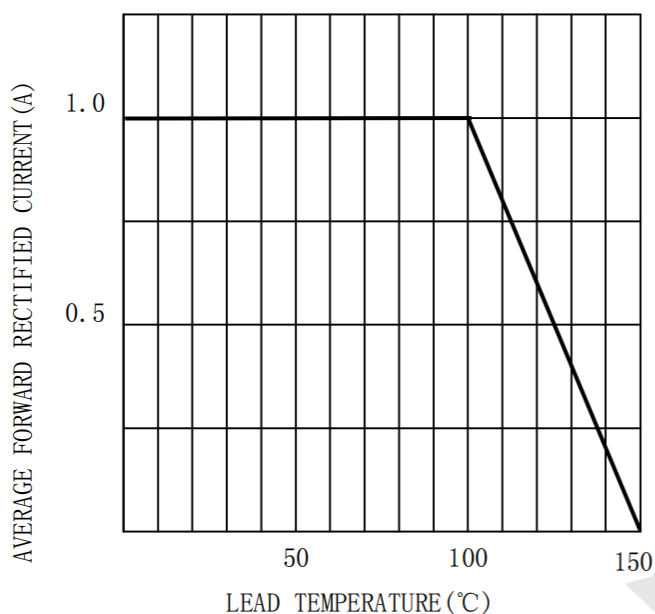


FIG. 2 TYPICAL FORWARD CHARACTERISTICS

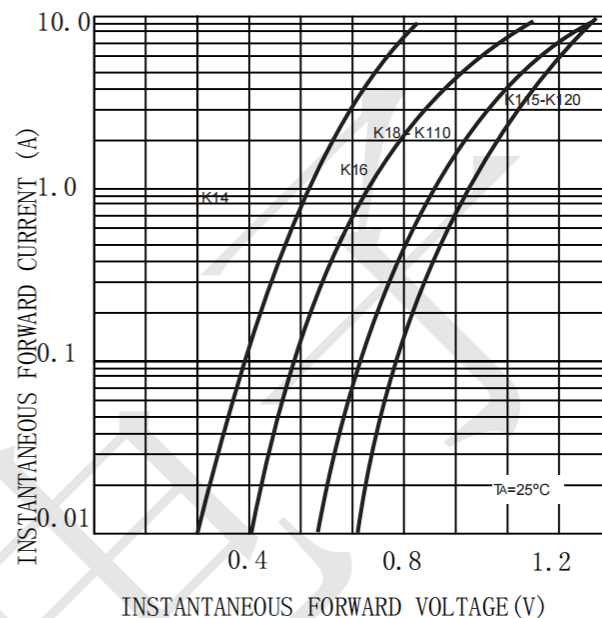


FIG. 3 MAXIMUM NON-REPEITIVE SURGE CURRENT

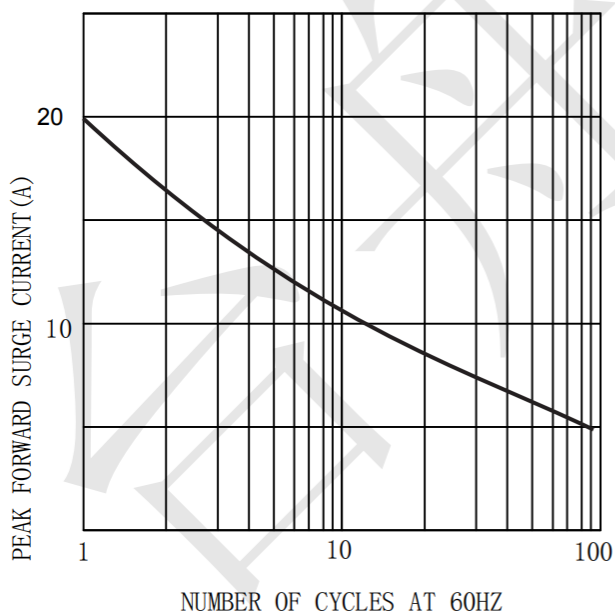
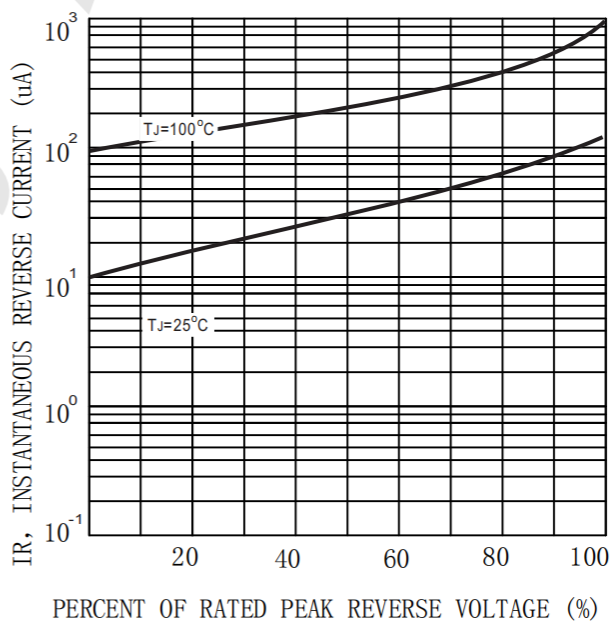
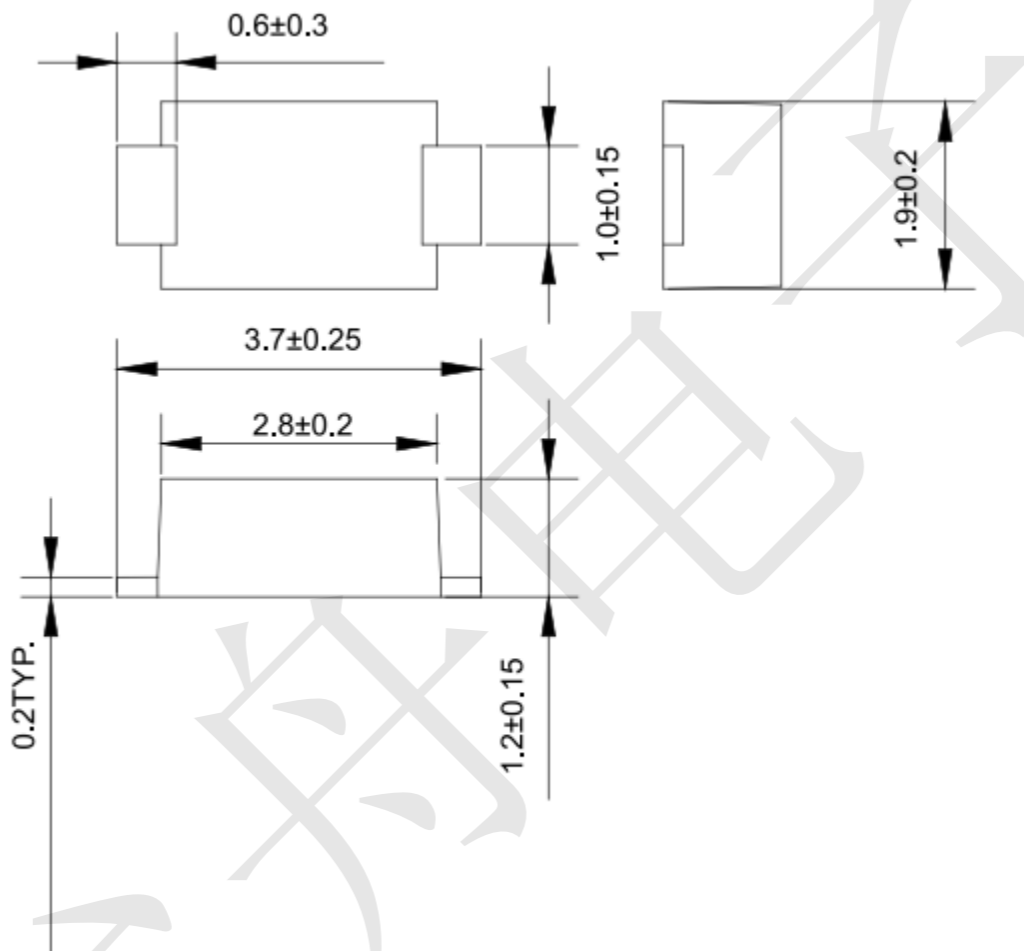


FIG. 4 TYPICAL REVERSE CHARACTERISTICS(per element)



Package information (Unit: mm)

SOD-23FL



Mounting Pad Layout (Unit: mm)

